# **MUR210**

Preferred Device

# SWITCHMODE™ Power Rectifier

SWITCHMODE power rectifiers are state-of-the-art devices that are designed for use in switching power supplies, inverters and as free wheeling diodes.

#### **Features**

- Ultrafast 20 Nanosecond Recovery Times
- 175°C Operating Junction Temperature
- Low Forward Voltage
- Low Leakage Current
- High Temperature Glass Passivated Junction
- These are Pb-Free Devices\*

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max for 10 Seconds, 1/16" from Case
- Polarity: Cathode Indicated by Polarity Band

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100 -	V
Average Rectified Forward Current (Square Wave Mounting Method #3) (Note 1)	I <sub>F(AV)</sub>	2.0 @ T <sub>A</sub> = 100°C	Α
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	35	A
Operating Junction Temperature and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +175	°C

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance, Junction–to–Ambient	$R_{\theta JA}$	See Note 3	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

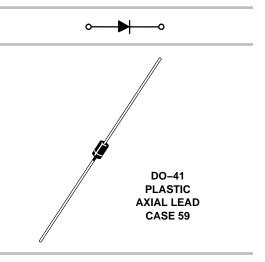
1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.



# ON Semiconductor®

http://onsemi.com

# ULTRAFAST RECTIFIERS 2 AMPERES, 100 VOLTS



#### **MARKING DIAGRAM**



A = Assembly Location

Y = Year WW = Work Week

= Pb–Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MUR210	Axial Lead*	1000 Units/Bag
MUR210G	Axial Lead*	1000 Units/Bag
MUR210RL	Axial Lead*	5000/Tape & Reel
MUR210RLG	Axial Lead*	5000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

**Preferred** devices are recommended choices for future use and best overall value.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# **MUR210**

# **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ (I_F = 2.0 \text{ A, } T_J = 150^{\circ}\text{C}) $ $ (I_F = 2.0 \text{ A, } T_J = 25^{\circ}\text{C}) $	V <sub>F</sub>	0.74 0.94	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_J = 150^{\circ}\text{C}$ ) (Rated DC Voltage, $T_J = 25^{\circ}\text{C}$ )	i <sub>R</sub>	50 2.0	μΑ
Maximum Reverse Recovery Time $ \begin{aligned} (I_F = 1.0 \text{ A, di/dt} = 50 \text{ A/}\mu\text{s}) \\ (I_F = 0.5 \text{ A, } I_R = 1.0 \text{ A, } I_{REC} = 0.25 \text{ A}) \end{aligned} $	t <sub>rr</sub>	30 20	ns
Maximum Forward Recovery Time (I <sub>F</sub> = 1.0 A, di/dt = 100 A/ $\mu$ s, I <sub>REC</sub> to 1.0 V)	t <sub>fr</sub>	20	ns

<sup>2.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

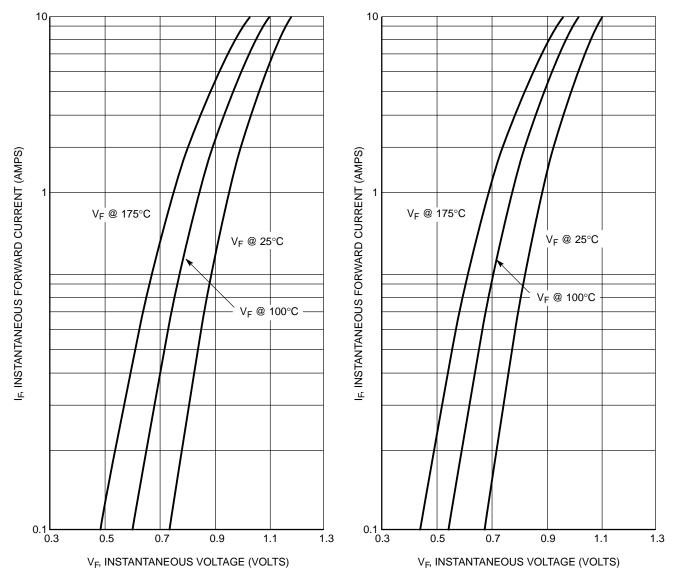


Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage

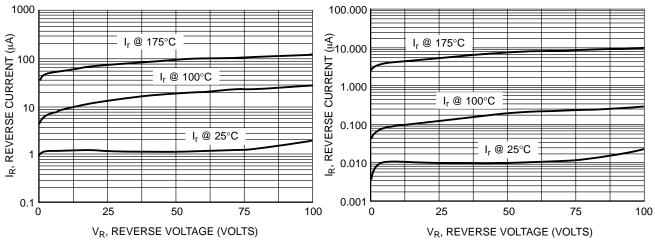


Figure 3. Maximum Reverse Current

**Figure 4. Typical Reverse Current** 

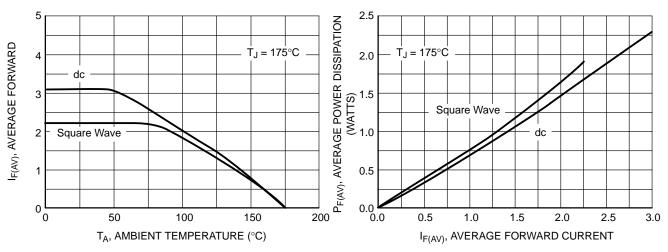


Figure 5. Current Derating

Figure 6. Power Dissipation

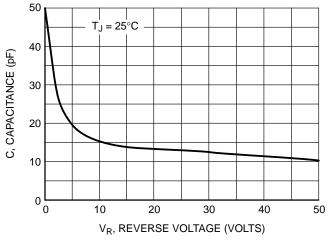


Figure 7. Maximum Capacitance

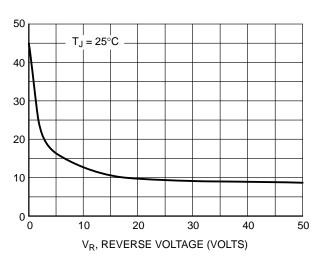


Figure 8. Typical Capacitance

C, CAPACITANCE (pF)

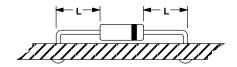
# **NOTE 3 – AMBIENT MOUNTING DATA**

Data shown for thermal resistance junction to ambient  $(R_{\theta JA})$  for the mountings shown is to be used as typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

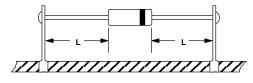
TYPICAL VALUES FOR  $R_{\theta \text{JA}}$  IN STILL AIR

Mounti	ng	Lead Length, L			
Method		1/8	1/4	1/2	Units
1		52	65	72	°C/W
2	$R_{\theta JA}$	67	80	87	°C/W
3			50		°C/W

#### **MOUNTING METHOD 1**

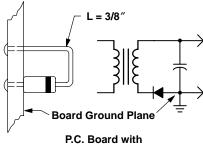


## **MOUNTING METHOD 2**



**Vector Pin Mounting** 

#### **MOUNTING METHOD 3**

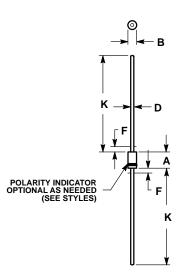


1–1/2" X 1–1/2" Copper Surface

#### **MUR210**

#### PACKAGE DIMENSIONS

**AXIAL LEAD** CASE 59-10 **ISSUE U** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- Y14.5M, 1982.
  CONTROLLING DIMENSION: INCH.
  ALL RULES AND NOTES ASSOCIATED WITH
  JEDEC DO-41 OUTLINE SHALL APPLY
  POLARITY DENOTED BY CATHODE BAND.
  LEAD DIAMETER NOT CONTROLLED WITHIN F
  DIMENSION.
- DIMENSION.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.161	0.205	4.10	5.20
В	0.079	0.106	2.00	2.70
D	0.028	0.034	0.71	0.86
F		0.050		1.27
K	1.000		25.40	

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